

REMARKS

Applicants have amended claim 1. Applicants have also amended claim 3, which has been only objected to as depending from claim 1, to appear in independent form. New claim 22 reflects the limitations of original claim 3 and finds support at page 4, lines 25-30, of the specification.

Claims 1 and 4 have been rejected under 35 USC 102(b) as anticipated by U.S. Patent No. 5,805,246 (Lee). Applicants respectfully traverse this rejection.

Claim 1 as amended states that the metal wiring is disposed over the first and second gate lines so as to connect the first and second gate lines and is located near an output portion of the vertical driving circuit. This amendment finds support, for example, at page 4, lines 17-19, and FIGS. 2A and 2B of the application. The claimed metal wiring is placed on the first and second gate lines to connect them after processing steps that may induce charges in the gate lines are completed, so that the induced charges do not harm the transistors formed in the driving circuits. See, for example, page 5, lines 3-7, of the specification.

The Examiner contends that Lee's bonding tape 6 corresponds to the claimed first gate line, Lee's gate line 1 to the claimed second gate line and Lee's gate pad 1' to the claimed metal wiring. Applicants respectfully disagree.

The claimed metal wiring connects the first and second gate lines after the processing of the first and second gate lines to avoid adverse effect of the induced charges, as explained above. Thus, the metal wiring is disposed over the first and second gate lines as claimed. On the other hand, Lee's gate pad 1', which the Examiner equates to the claimed metal wiring, serves as a bonding pad for electric connection to Lee's printed circuit board 7 that contains drivers. Since the gate line 1 and the gate pad 1' are formed on Lee's substrate 3 and the printed circuit board 7 is assembled as an external device element, the bonding tape 6 connecting the substrate 3 and the circuit board 7 must be placed on the gate pad 1' which has been already formed on the substrate 3. See, for example, column 4, lines 6-15, of Lee. Thus, the gate pad 1' cannot be and is not placed above the bonding tape 6, as it would have to be if Lee were to anticipate the invention as

claimed. Nothing in Lee teaches or suggests that Lee's bonding tape 6 is first placed on the substrate 3 and then the gate pad 1' is formed on the bonding tape 6.

The rejection of claims 1 and 4 under 35 USC 102(b) on Lee should be withdrawn because Lee does not teach or suggest the claimed metal wiring that is disposed over the first and second gate lines.

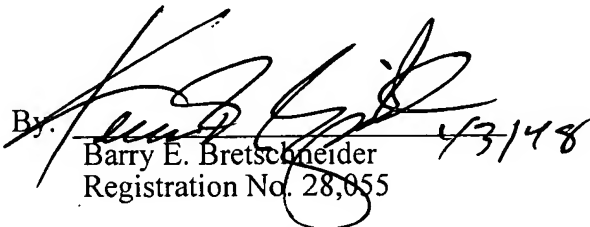
The remaining rejection relies on Lee and thus should be withdrawn as well because Lee does not provide the teachings for which it is cited.

In light of the above, a Notice of Allowance is solicited.

In the event that the transmittal letter is separated from this document and the Patent and Trademark Office determines that an extension and/or other relief is required, applicants petition for any required relief including extensions of time and authorize the Commissioner to charge the cost of such petitions and/or other fees due in connection with the filing of this document to **Deposit Account No. 03-1952**, referencing Docket No. **606402014800**.

Respectfully submitted,

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